

Notes: (Unless Otherwise Specified).

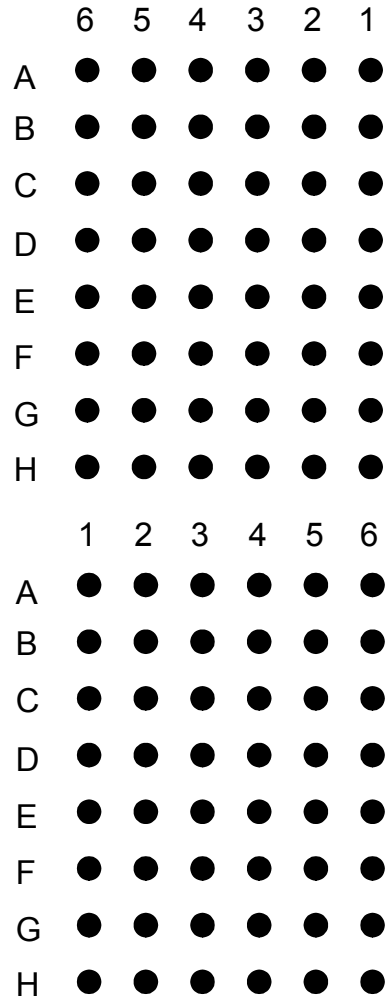
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.28mm [11 MIL].
- 5) PAD Cu DIAMETER: 0.4mm [16 MIL].
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (OPTIONAL).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA48T.75-6x8B	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	NO
BGA48T.75C-6x8B	Sn63/Pb37	Sn63	NO	NO

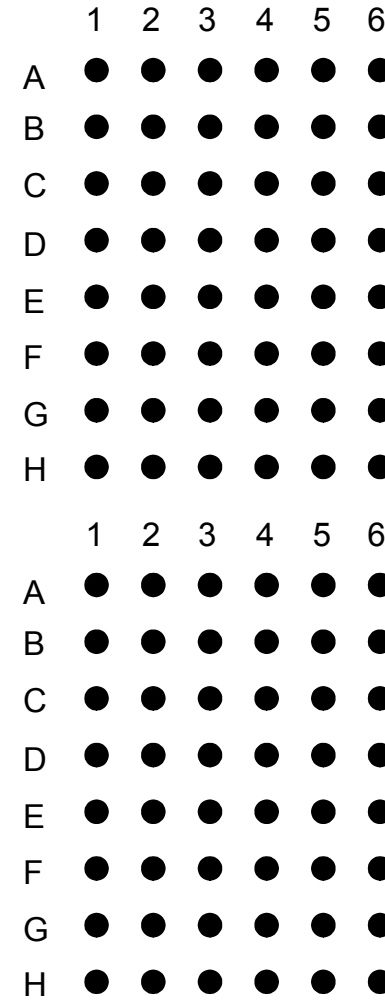
APPROVALS	DATE	TopLine®			
DRAWN T. Au	02/24/13	TITLE BGA48T.75-6x8B DUMMY			
ENG M. Hart	02/24/13				
MFG		SCALE	SIZE A	DRAWING NO. 576800	REV A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD

BOTTOM SIDE (TOP X-RAY VIEW)



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.4mm [16 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL]. (OPTIONAL)
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.28mm [11 MIL].

TopLine®			
TITLE		BGA48T.75-6x8B DUMMY	
SCALE	SIZE	DRAWING NO.	REV
	A	576800	A
DO NOT SCALE DRAWING			SHEET 2 OF 2